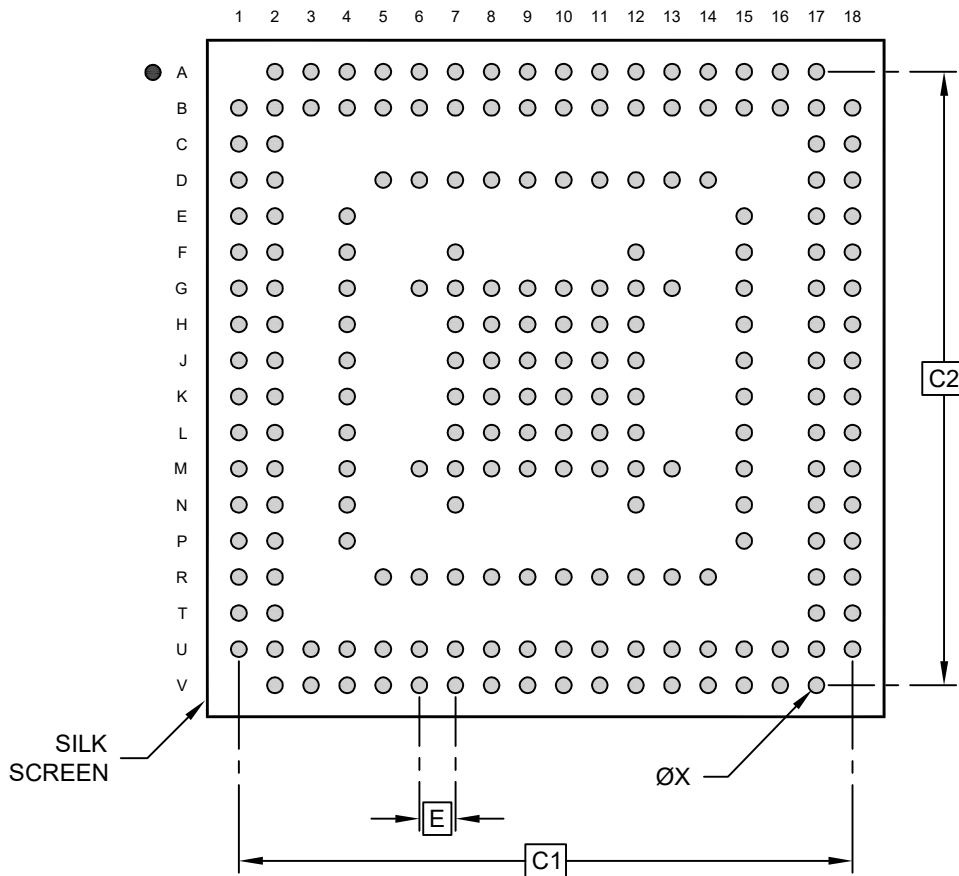


## 208-Ball Fine-Pitch Ball Grid Array Package (8MX) - 15x15x1.19 mm Body [TFBGA]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1		13.60 BSC		
Contact Pad Spacing	C2		13.60 BSC		
Contact Pad Diameter	X				0.35

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process